

S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Examiner: James Mitchell

Serial No.: 10/722,838

Group Art Unit: 2813

Filed: November 26, 2003

Docket: 303.601US3

Confirmation No.: 8165

Title: METHOD OF PACKAGING AT A WAFER LEVEL

INFORMATION DISCLOSURE STATEMENT

MS RCE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

Applicant brings to the attention of the Examiner the following Office Actions and responses associated with one or both of the inventors of the instant application and/or the assignee of the instant application. This material is available and accessible at the United States Patent and Trademark Office.

AN ADHESIVE LAYER FOR AN ELECTRONIC APPARATUS HAVING MULTIPLE SEMICONDUCTOR DEVICES

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Non Final Office Action mailed 07-18-2001, 10 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Response filed 10-18-2001 to Non Final Office Action mailed 07-18-2001, 16 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Final Office Action mailed 03-01-2002, 7 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Response filed 06-03-2002 to Final Office Action mailed 03-01-2002, 13 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Final Office Action mailed 09-19-2002, 11 pgs

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Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Response filed 11-19-2002 to Final Office Action mailed 09-19-2002, 10 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Advisory Action mailed 01-07-2003, 3 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Non Final Office Action mailed 03-18-2003, 8 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Response filed 06-13-2003 to Non Final Office Action mailed 03-18-2003, 13 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Notice of Allowance mailed 08-22-2003, 7 pgs

Application Serial No. 09/505,018 (Atty. Ref. 303.601US1) Amendment Under 37 CFR 1.312 filed 11-24-2003, 8 pgs

ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Non Final Office Action mailed 11-02-2005, 7 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Response filed 02-02-2006 to Non Final Office Action mailed 11-02-2005, 13 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Final Office Action mailed 05-02-2006, 9 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Response filed 08-31-2006 to Final Office Action mailed 05-02-2006, 14 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Non Final Office Action mailed 10-20-2006, 8 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Response filed 01-17-2007 to Non Final Office Action mailed 10-20-2006, 15 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Final Office Action mailed 04-23-2007, 9 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Response filed 06-25-2007 to Final Office Action mailed 04-23-2007, 18 pgs

Application Serial No. 10/723,474 (Atty. Ref. 303.601US2) Advisory Action mailed 07-24-2007, 3 pgs

Application Serial No. 10/723474 (Atty Ref. 303.601US2) Non-Final Office Action mailed 12/13/2007, 10 Pages

WAFER LEVEL PRE-PACKAGED FLIP CHIP

Application Serial No. 11/460,093 (Atty. Ref. 303.601US5) Non-Final Office Action mailed 1-02-08, 18 pgs

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications, and Non-Published Applications identifiable by USPTO Serial Number, are no longer required to be provided to the Office. Notification of this change to this effect was provided in the United States Patent and Trademark Office OG Notice dated October 19, 2004. Thus, Applicant has not included copies of any US Patents or US Patent Applications identifiable by serial number that may be cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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Date

9 April 2008

By



David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 9th day of April, 2008.

Name

Amy Moriarty

Signature

